

APM2300AC-TRG-VB Datasheet

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^e	Q _g (Typ.)			
	0.028 at V _{GS} = 4.5 V	6 ^a				
20	0.042 at V _{GS} = 2.5 V	6 ^a	8.8 nC			
	0.050 at V _{GS} = 1.8 V	5.6				

FEATURES

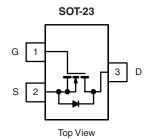
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converters
- Load Switch for Portable Applications



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V_{DS}	20	V		
Gate-Source Voltage		V_{GS}	± 12	v	
	T _C = 25 °C		6 ^a		
Continuous Drain Comment /T 150 °C\	T _C = 70 °C	I _D	5.1		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C		5 ^{b, c}		
	T _A = 70 °C		4 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	20		
0 11 0 0 0 1	T _C = 25 °C		1.75		
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	1.04 ^{b, c}		
	T _C = 25 °C	- P _D	2.1		
Maximum Bayer Dissination	T _C = 70 °C		1.3	w	
Maximum Power Dissipation	T _A = 25 °C		1.25 ^{b, c}	VV	
	T _A = 70 °C	•	0.8 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		
Soldering Recommendations (Peak Tempera	ature)		260		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	80	100	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	60	- C/VV		

Notes:

- a. Package limited
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 125 $^{\circ}\text{C/W}.$
- e. Based on $T_C = 25$ °C.

服务热线:400-655-8788

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static			l .		! 		
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	/pe/Ti		25		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_{D} = 250 \mu A$		- 2.6		mv/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	0.45		1.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	= = =		1 1		10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		0.028			
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 4.7 \text{ A}$		0.042		Ω	
		V _{GS} = 1.8 V, I _D = 4.3 A		0.050		╡	
Forward Transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 5.0 A		24		S	
Dynamic ^b	1 -10					L	
Input Capacitance	C _{iss}			865			
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		105		pF	
Reverse Transfer Capacitance	C _{rss}	20 / do /		55			
Tieverse mansier dapaonarioe		V _{DS} = 10 V, V _{GS} = 5 V, I _D = 5.0 A		12	18	-	
Total Gate Charge	Qg	23 · , d3 · , b · ·		8.8	14	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		1.1			
Gate-Drain Charge	Q _{gd}	D3 - 7 G3 - 7 D		0.7			
Gate Resistance	R _g	f = 1 MHz	0.5	2.4	4.8	Ω	
Turn-On Delay Time	t _{d(on)}			8	16		
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		17	26	-	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4$ A, $V_{GEN}=4.5$ V, $R_g=1$ Ω		31	47	-	
Fall Time	t _f			8	16	-	
Turn-On Delay Time	t _{d(on)}			5	10	ns	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		13	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4$ A, $V_{GEN}=5$ V, $R_g=1$ Ω		21	32		
Fall Time	t _f			6	12	-	
Drain-Source Body Diode Characteristic							
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			1.75		
Pulse Diode Forward Current	I _{SM}	-			20	A	
Body Diode Voltage	V _{SD}	I _S = 4 A, V _{GS} = 0 V		0.75	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	- 40		12	20	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			5	10	nC	
Reverse Recovery Fall Time	t _a	$I_F = 4 \text{ A}$, $dI/dt = 100 \text{ A/}\mu\text{s}$, $T_J = 25 ^{\circ}\text{C}$		7	-	-	
Reverse Recovery Rise Time	t _b			5		ns	

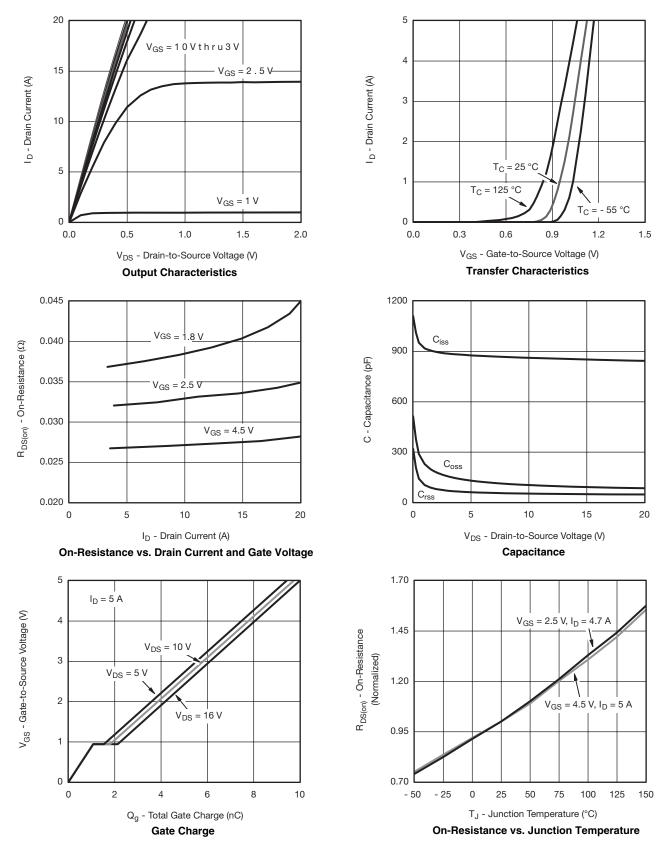
Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

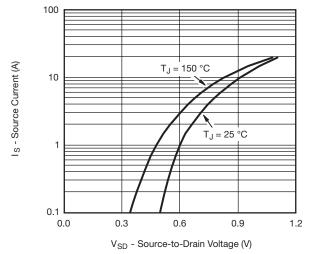


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

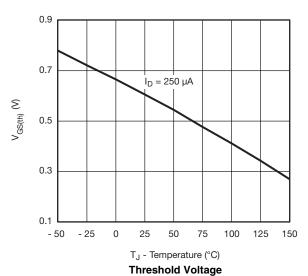




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Source-Drain Diode Forward Voltage

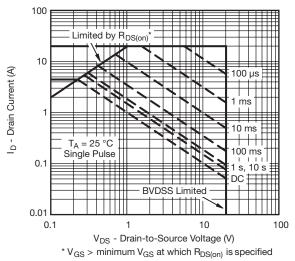


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On-Resistance vs. Gate-to-Source Voltage



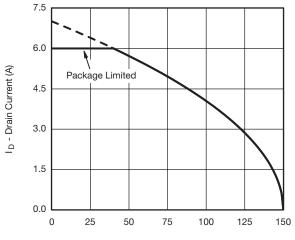
Single Pulse Power (Junction-to-Ambient)



Safe Operating Area, Junction-to-Ambient

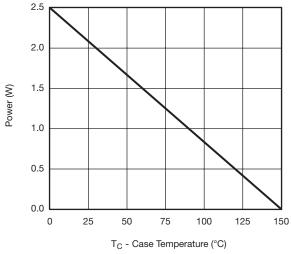


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

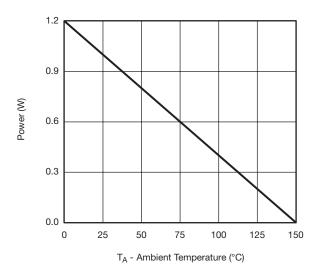


T_C - Case Temperature (°C)

Current Derating*







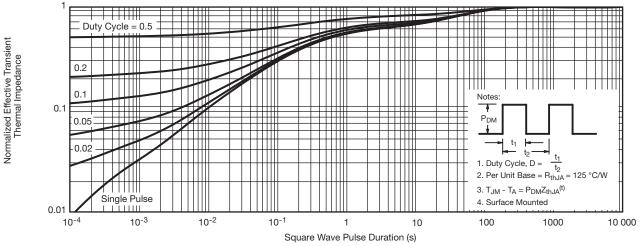
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

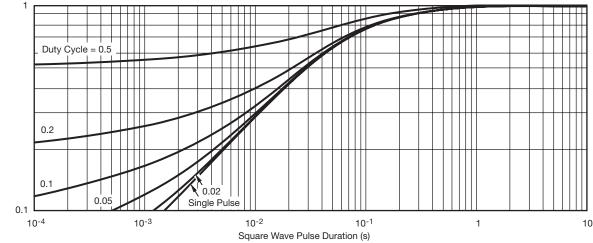
Normalized Effective Transient Thermal Impedance



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



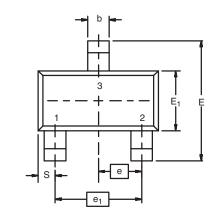
Normalized Thermal Transient Impedance, Junction-to-Ambient

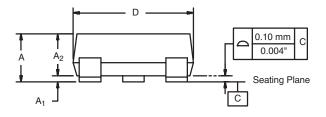


Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.9	0 BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	Jul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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